

ORDATION FORM COVER SHEET U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Affice **PATENTS ONLY** 101677476 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy theree 1 Name of conveying party(ies): Name and address of receiving party(ies): Taiwan Semiconductor Manufacturing Co. Yi-Hsun Wu No. 121 Park Avenue 3 Jian-Hsing Lee Science-Based Industrial Park Shui-Hung Chen Hsin-Chu, Taiwan, R.O.C. Jiaw-Ren Shih Nature of conveyance: Additional name(s) & address(es) attached □ Yes ☑ No Assignment Merger ☐ Security Agreement ☐ Change of Name 09827194 Other: Execution Date: January 3, 2001 4 Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: 01-03-01 B. Patent No(s) A. Patent Application No(s). Additional numbers attached? □ Yes ☑ No 5 Name and address of party to whom correspondence Total number of applications and patents involved: concerning document should be mailed: RANDY W. TUNG Total fee (37 CFR 3.41) \$40.00 Tung & Associates 838 W. Long Lake Road Enclosed Suite 120 Bloomfield Hills, Michigan 48302 Authorized to be charged to deposit account 50-0484 Deposit Account Number: 04/10/2001 AZEKBAWI 00000040 09827194 (Attach duplicate copy of this page if paying by deposit U:581 40.00 NP DO NOT USE THIS SPACE

9 Statement and signature.

the original document.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of

Randy W. Tung Name of Person Signing Registration No. 31,311

Signature

April 5, 2001 Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

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ASSIGNMENT

WHEREAS, we, <u>YI-HSUN WU, JIAN-HSING LEE, SHUI-HUNG CHEN and JIAN-REN SHIH</u> have invented certain improvements in INTEGRATED CIRCUIT HAVING IMPROVED ESD PROTECTION for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, <u>YI-HSUN WU, JIAN-HSING LEE, SHUI-HUNG CHEN and JIAN-REN SHIH</u>, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the <u>3rd</u> day of <u>Quantary</u>, 200<u>4</u>, preparatory to obtaining Letters Patent of the United States thereon, and in and to said

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PATENT REEL: 011687 FRAME: 0218 application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Yi-Hsun Wn.

Jian-Hsing Lee

Shui-HUNG CHEN

Janv-Ren SAUJ JIAN-REN SHIH

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

RECORDED: 04/05/2001

PATENT REEL: 011687 FRAME: 0219